October 21 (Wed.), 2026

[Oral 07] Post-CMP Cleaning / Defect Engineering

11:25-12:50

International Conference Hall (B1F)

● Session Chair: Jingoo Park (Hanyang Univ., Korea)

11:25-11:50 [Oral 07-1]	**[Invited]** Evolution of Cu PCMP Technology from Mature to Advanced Nodes Ping Hsu, Peter Sun, and Jacky Cheng (Qnity Electronics Inc., Taiwan)
11:50-12:10 ★[Oral 07-2]	Comparative Evaluation of Ammonium- and QAC-Based Alkaline Cleaning Chemistries for Molybdenum Post-CMP Cleaning Gyeongwon Lee, Palwasha Jalalzai (Hanyang Univ., Korea), Junsang Lee, Gayoung Kim, In-Kwon Kim, Sangkyun Kim (Samsung Electronics Co., Ltd., Korea), Tae-Gon Kim, Jihoon Seo, and Jin-Goo Park (Hanyang Univ., Korea)
12:10-12:30 ★[Oral 07-3]	Additive-Free Post-CMP Cleaning for Fine Ceria Particle Removal with Gas-Dissolved Water Hyeonjeong Lee, Donghwan Choi, Jinhyoung Lee, Yechan Kim, and Taesung Kim (Sungkyunkwan Univ., Korea)
12:30-12:50 ★[Oral 07-4]	Effect of pH on Acoustic Bubble Dynamics, Particle Removal Efficiency, and Pattern Damage During Megasonic Cleaning Mir Jalal Khan (Hanyang Univ., Korea), Yunhee Cho, Wonseob Cho (BASF, Korea), Andreas Klipp (BASF SE, Germany), Jihoon Seo, and Jin-Goo Park (Hanyang Univ., Korea)